

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL. NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
100861.17	02/26/2002	226	735	222	Lewis

**APPLICANTS: Bojkov Christo; Coffman Phillip; Smith Patricia;

CONTINUING DATA VERIFIED:

THIS APPLN CLAIMS BENEFIT OF 60/342,949 12/21/2001

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** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		TI: 33887	
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no			
Verified and Acknowledged Examiners's initials			
TITLE: Wafer level method for direct bumping on copper pads in integrated circuits			

NOTICE OF ALLOWANCE MAILED		STAFF	
		Assistant Examiner	
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheet 1 of 1	Sheet 2 of 1
		Application Examiner	
TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
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